R825 2U Flagship Versatile Server

The R825 is a premium 2U rack server powered by 4th/5th Gen Intel® Xeon® Scalable processors, boasting robust performance and stable operation. Designed specifically for flexible resource allocation to meet diverse industry demands, it stands out in core application fields such as cloud computing, HPC, cloud storage, big data, virtualization, enterprise systems, and beyond.



Extreme Performance with Scalability

Specifications

Model	R825
Processor	Supports 2*4th/5th Gen Intel Xeon® Scalable Processors (TDP 385W)
Memory	Up to 32*DDR5 slots, up to 5600MHz
RAID	Supports BCM 95 series RAID cards.
Storage	Up to 12*3.5" or 28*2.5" hot-swappable drives (24*NVMe compatible) Internal: 2*SATA/PCIe M.2 Onboard supports for 16*SATA drives (no external controller required)
Network Interface	1*OCP 3.0 slot with NCSI Optional interfaces: 2*GE, 2*10GE, 2*25GE, 2*100GE, 2*200GE
PCIe Expansion	Up to 8*PCIe 5.0 slots + 1*OCP 3.0 slot
Additional Interfaces	Rear: 1*RJ-45 management port, 2*USB 3.0, 1*VGA Front:2*USB 3.0 + VGA
Power Supply	Supports 1300W/2000W CRPS Titanium/Platinum PSU (hot-swappable, 1+1 redundant) Voltage: 100-240V AC (refer to nameplate)
Fan	6*hot-swappable fans (N+2 redundancy)

Management	Integrated BMC with 1Gbps RJ-45 port Supports Redfish, SNMP, IPMI 2.0, HTML5/iKVM remote control BMC dual-flash backup
OS Support	Windows Server, RHEL, SLES, CentOS, Ubuntu, VMware ESXi, etc.
Operating Temperature	5℃ ~ 45℃
Chassis Dimensions	770mm (L)* 482mm (W) *87mm (H)
Packaging Dimensions	1000mm (L)*600mm (W)*260mm (H)
Weight	Max 40kg (varies by configuration)

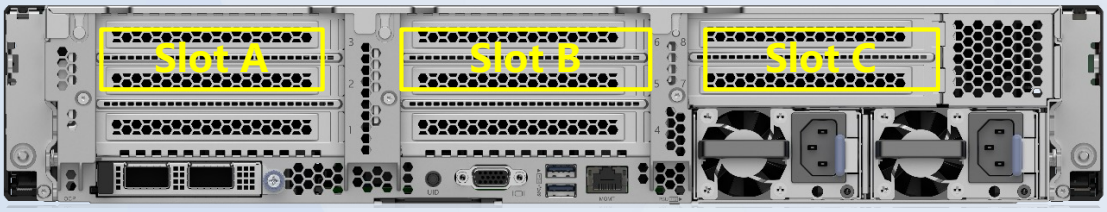
Product View



Front View (12*3.5-inch SAS/SATA/NVMe model)



Front View (24*2.5-inch SAS/SATA/NVMe model)



Rear View

The slot A/B supports 1*PCIe 5.0 x16+2*PCIe 5.0 x8 riser card.

The slot A/B can be inserted a baffle when the riser is not on the bezel.

The slot C supports 4*2.5(SAS/SATA/NVMe)/2*2.5(SAS/SATA)/2*full-height PCIe interface cards.

Product Features

High-Density Computing Power

Engineered for extreme density: 2*385W CPUs plus 32*DDR5 DIMMs integrated in a slim 2U form factor. Accelerate application performance with enhanced high-speed connectivity. Flexible scalability is guaranteed by versatile OCP NICs and PCIe 5.0 slots, boosting transmission speeds by 100%.

High Reliability and Security

Delivering 50% higher heat dissipation efficiency compared with single heat sink solutions. Adopting remote heat pipe cooling technology, it ensures reliable thermal dissipation and superior temperature adaptability. Cutting system downtime by 66%, the proprietary AI-powered memory fault self-healing technology guarantees uninterrupted, stable system operation.

Efficient Energy Saving

Industry-leading power supply technology for higher efficiency, it delivers an industry-top power conversion rate, with power loss 12.5% lower than the industry average, cutting overall energy consumption by up to 8% versus standard industry solutions.Proprietary smart algorithms minimize power draw for fans and CPUs to further reduce energy use.

Intelligent O&M

Delivering 20× higher upgrade efficiency, the tool-free design enables fast component assembly and disassembly to shorten O&M time. Out-of-band visual management supports precise remote localization of physical device status and information, enabling intelligent full-lifecycle services for the product.